Automatic Inline Vapour Phase Reflow Oven

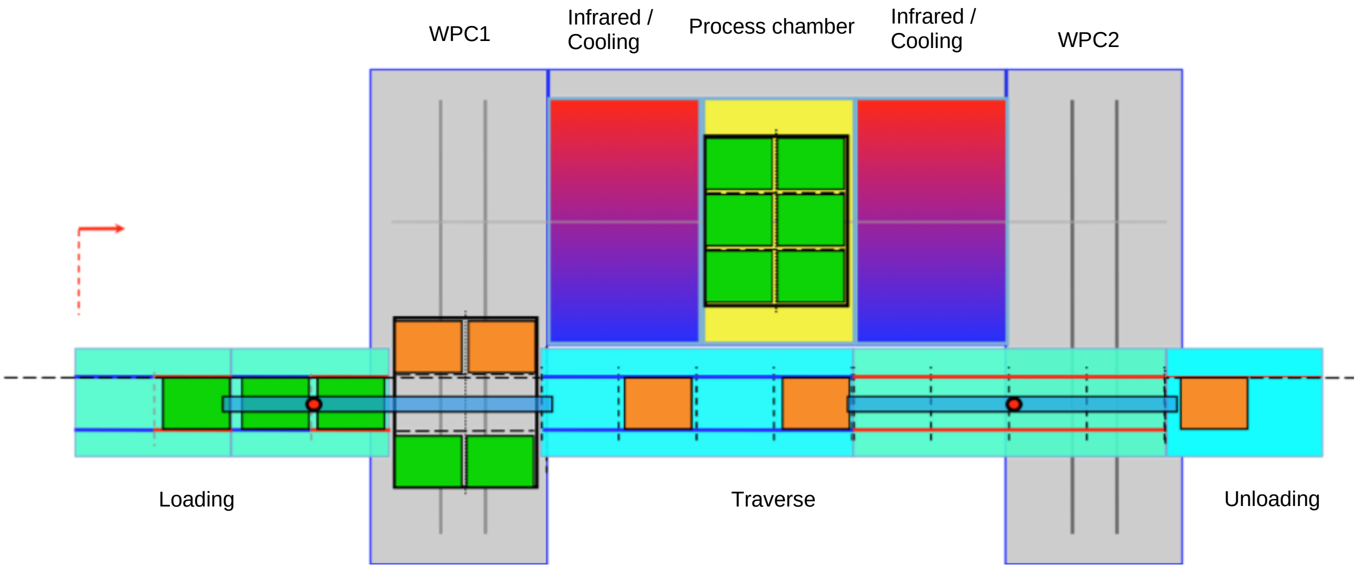
The CX Series is a machine dedicated for high volume and a variety of board sizes. The machine is capable of running in inline or in batch mode. Patented Double Soft Vapour is a feature with simultaneously two work piece carriers thus improving the throughput. Thanks to its unique design it also works simultaneously with one work piece carrier being loaded automatically while the other one can be loaded manually. One solder chamber, two loading positions and heating chambers - each makes the machine perfect for high throughput allowing to reach cycle times of 20 seconds per assembly. Its size allows to load a large amount of boards simultaneously onto a work piece carrier thus letting them all get soldered in one go. While one carrier is in the solder chamber the second gets unloaded and at the same time loaded with fresh board again. Soldering is possible regardless of assembly weight with the same profile and with a high repeatability.

Features:

- Comfortable touch screen display with integrated PC
- Permanent data collection
- Unlimited program memory with a large amount of sample programs
- Pilot mode, measurement channel for easy temperature-controlled soldering and setting up of profiles
- Energy management system
- Heating power monitoring
- Network capable
- Password protected operation levels
- Intelligent Profiling System (IPS) for high-end thermal profile control
- Buffer in the loading and unloading area
- Automatic loading and unloading Work Piece Carrier
- Automatic adjustment of transport lane width and work piece carrier
- Signal light tower
- Patented vibration and maintenance free transport system
- Multiple chamber design and medium recovery results in a very low fluid consumption
- Fluid level control and automatic filtering
- Medium recovery system
- Integrated cooling fans
- Minimal maintenance and wear due to all moving parts mounted outside of the process chamber
- Cool handling – transport system in cool area
- Easy access to solder chamber for cleaning and maintenance purposes
- Observation window into the solder chamber
- Exhaust connection
- Several Emergency stop buttons
- Storage compartment for carrier

Options:

- Infrared pre-heating
- Batch carrier and stainless-steel grid
- Adapter for double sided boards for batch carrier
- Online Temperature Recording Software (VP-Control) for data analysis and storage
- Multi-Level Mode for rapid switching between different soldering heights within the vapour blanket
- Up to 2 measurement channels per Work Piece Carrier (WPC1 and WPC2)
- UPS – Uninterruptable Power Supply
- ReSy – a device for repair of QFPs and BGAs
- Exhaust system extensions
- Chiller for inside or outside use with automatic standby control



Technical data:

	CX600	CX800
Depth	1980 mm (77.95“)	2390 mm (94.09“)
Length	5950 mm (234.25“)	
Height	1500 mm (59.06“)	
Weight	1980 kg (4365.15 lbs)	2090 kg (4607.66 lbs)
Max. PCB size batch mode	680 x 646 x 65 mm 26.78 x 25.43 x 2.56”	680 x 826 x 65 mm 26.78 x 32.52 x 2.56”
Max. PCB size inline mode	680 x 305 x 45 mm 26.78 x 12.01 x 1.77”	680 x 510 x 45 mm 26.78 x 20.08 x 1.77”
Max. load on single carrier	7 kg (15.43 lbs)	
Liquid agent filling	40 kg (88.18 lbs)	45 kg (99.21 lbs)
Water connection	½” / 2,5 – 5 bar	
Max. heating capacity	7,6kW	10,4kW
Average power consumption	3,9 kW/h	5,3 kW/h
Power supply	400/230 VAC, 50/60Hz	
Main fuse	16A „gl“ or „C“	32A „gl“ or „C“

Specifications subject to change without prior notice